



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



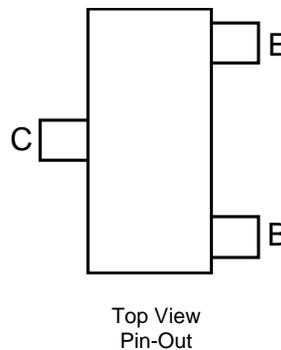
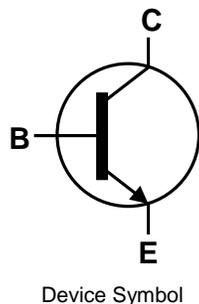
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Features

- $BV_{CEO} > 400V$
- $I_C = 225mA$ High Continuous Collector Current
- $I_{CM} = 1A$ Peak Pulse Current
- 500mW Power Dissipation
- Excellent h_{FE} Characteristics Up to 100mA
- Complementary PNP Type: NK-FMMT558

Mechanical Data

- Package: SOT23
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.008 grams (Approximate)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|------------------------------|------------------|-------|------|
| Collector-Base Voltage | V _{CB0} | 400 | V |
| Collector-Emitter Voltage | V _{CEO} | 400 | V |
| Emitter-Base Voltage | V _{EBO} | 7 | V |
| Continuous Collector Current | I _C | 225 | mA |
| Peak Pulse Current | I _{CM} | 1 | A |
| Base Current | I _B | 200 | mA |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation (Note 5) | P _D | 500 | mW |
| Thermal Resistance, Junction to Ambient (Note 5) | R _{θJA} | 250 | °C/W |
| Thermal Resistance, Junction to Lead (Note 6) | R _{θJL} | 197 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

ESD Ratings (Note 7)

| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | ≥ 400 | V | C |

- Notes:
5. For a device surface mounted on 15mm X 15mm X 1.6mm FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 6. Thermal resistance from junction to solder-point (at the end of the collector lead).
 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

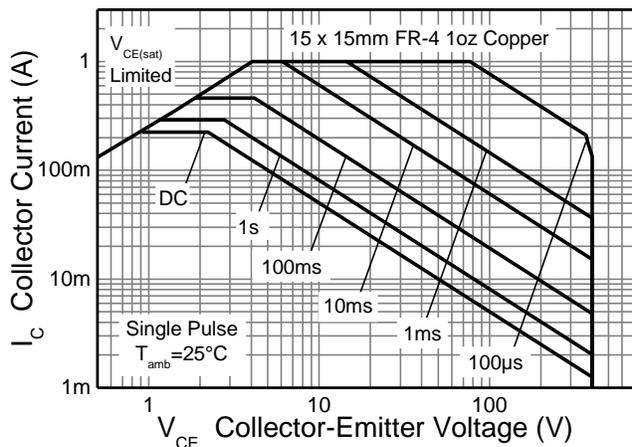


Figure 1. Safe Operating Area

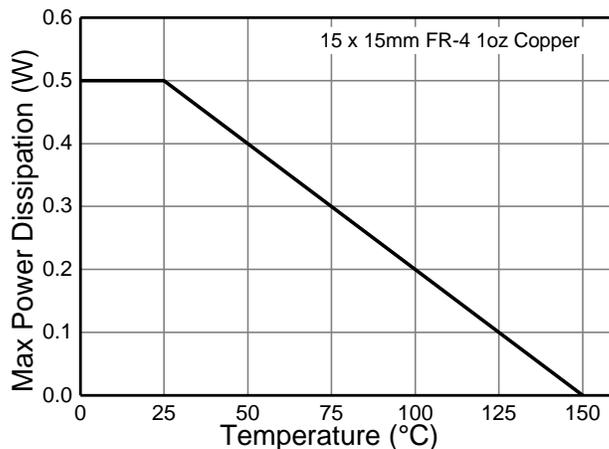


Figure 2. Derating Curve

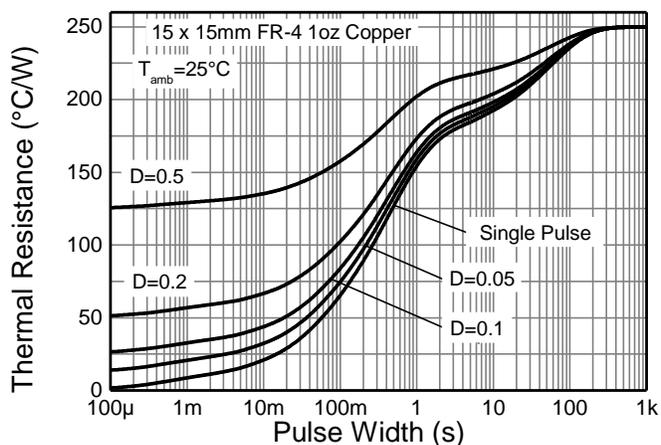


Figure 3. Transient Thermal Impedance

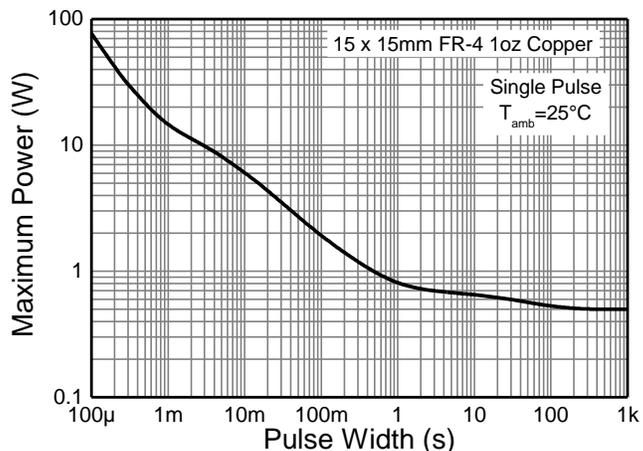


Figure 4. Pulse Power Dissipation

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|---------------|------------------|------|------------|----------|--|
| Collector-Base Breakdown Voltage | BV_{CBO} | 400 | — | — | V | $I_C = 100\mu\text{A}$ |
| Collector-Emitter Breakdown Voltage (Note 8) | BV_{CEO} | 400 | — | — | V | $I_C = 10\text{mA}$ |
| Emitter-Base Breakdown Voltage | BV_{EBO} | 7 | — | — | V | $I_E = 100\mu\text{A}$ |
| Collector Cutoff Current | I_{CBO} | — | — | 100 | nA | $V_{CB} = 320\text{V}$ |
| Emitter Cutoff Current | I_{EBO} | — | — | 100 | nA | $V_{EB} = 5.6\text{V}$ |
| Collector Emitter Cutoff Current | I_{CES} | — | — | 100 | nA | $V_{CE} = 320\text{V}$ |
| Static Forward Current Transfer Ratio (Note 8) | h_{FE} | 100 100 15 | — | 300 | — | $I_C = 1\text{mA}, V_{CE} = 10\text{V}$ $I_C = 50\text{mA}, V_{CE} = 10\text{V}$ $I_C = 100\text{mA}, V_{CE} = 10\text{V}$ |
| Collector-Emitter Saturation Voltage (Note 8) | $V_{CE(sat)}$ | — | — | 200 500 | mV mV | $I_C = 20\text{mA}, I_B = 2\text{mA}$ $I_C = 50\text{mA}, I_B = 6\text{mA}$ |
| Base-Emitter Turn-On Voltage (Note 8) | $V_{BE(on)}$ | — | — | 0.9 | V | $I_C = 50\text{mA}, V_{CE} = 10\text{V}$ |
| Base-Emitter Saturation Voltage (Note 8) | $V_{BE(sat)}$ | — | — | 0.9 | V | $I_C = 50\text{mA}, I_B = 5\text{mA}$ |
| Output Capacitance | C_{obo} | — | — | 5 | pF | $V_{CB} = 20\text{V}, f = 1\text{MHz}$ |
| Transition Frequency | f_T | 50 | — | — | MHz | $V_{CE} = 20\text{V}, I_C = 10\text{mA}, f = 20\text{MHz}$ |
| Turn-On Time | t_{on} | — | 135 | — | ns | $V_{CE} = 100\text{V}, I_C = 50\text{mA}$ |
| Turn-Off Time | t_{off} | — | 2260 | — | ns | $I_{B1} = 5\text{mA}, I_{B2} = -10\text{mA}$ |

Note: 8. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

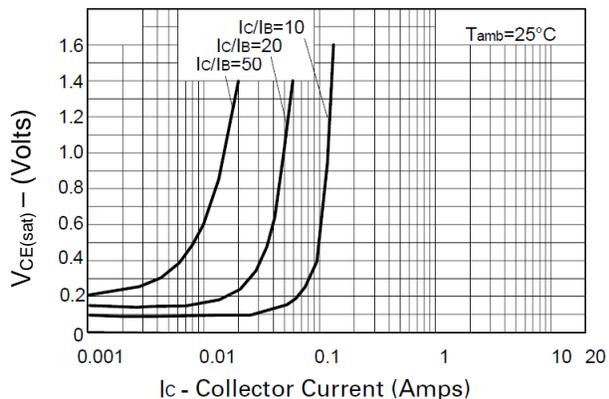


Figure 5. $V_{CE(sat)}$ v I_c

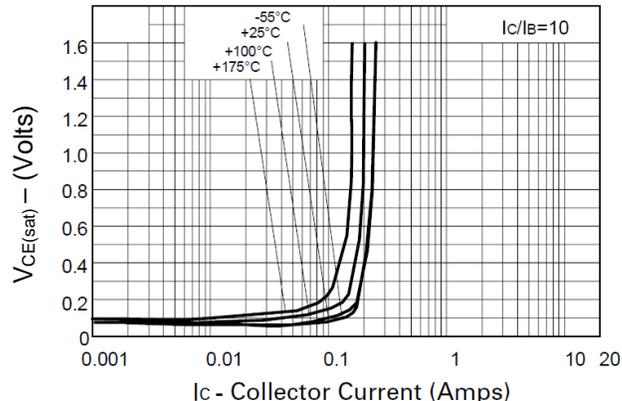


Figure 6. $V_{CE(sat)}$ v I_c

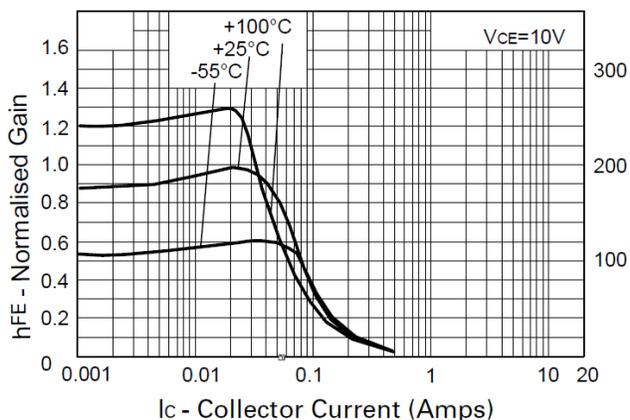


Figure 7. h_{FE} v I_c

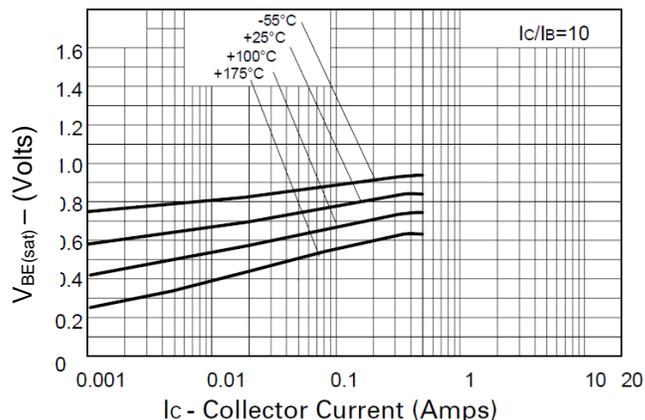


Figure 8. $V_{BE(sat)}$ v I_c

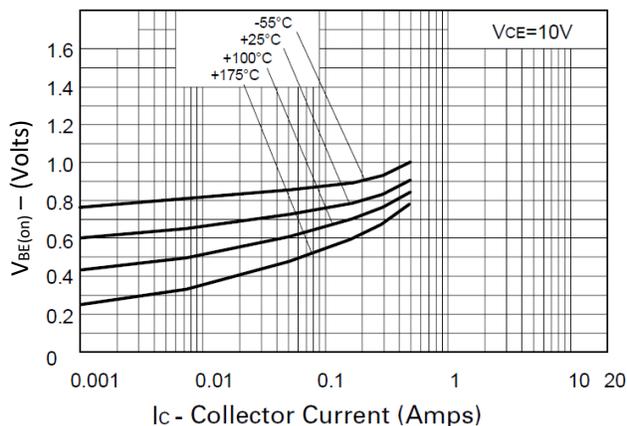
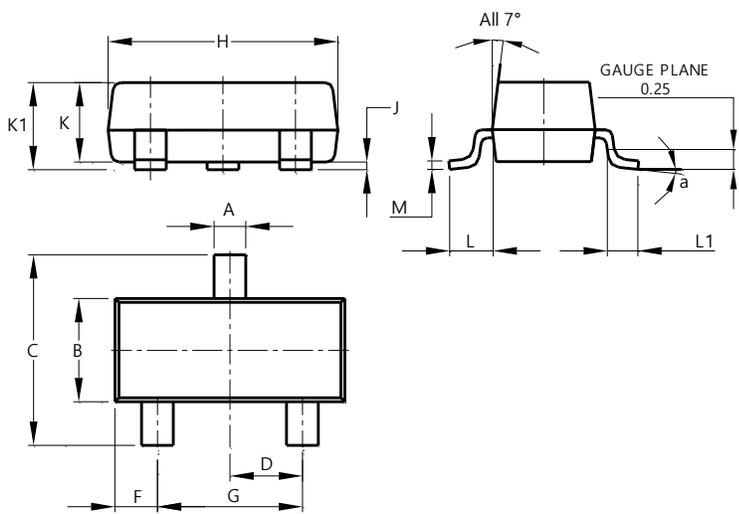


Figure 9. $V_{BE(on)}$ v I_c

Package Outline Dimensions

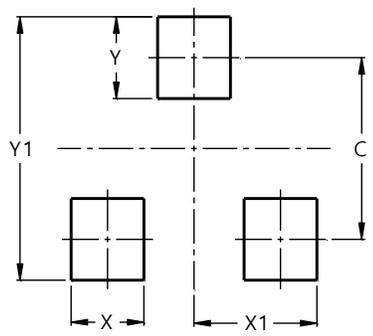
SOT23



| SOT23 | | | |
|----------------------|-------|-------|-------|
| Dim | Min | Max | Typ |
| A | 0.37 | 0.51 | 0.40 |
| B | 1.20 | 1.40 | 1.30 |
| C | 2.30 | 2.50 | 2.40 |
| D | 0.89 | 1.03 | 0.915 |
| F | 0.45 | 0.60 | 0.535 |
| G | 1.78 | 2.05 | 1.83 |
| H | 2.80 | 3.00 | 2.90 |
| J | 0.013 | 0.10 | 0.05 |
| K | 0.890 | 1.00 | 0.975 |
| K1 | 0.903 | 1.10 | 1.025 |
| L | 0.45 | 0.61 | 0.55 |
| L1 | 0.25 | 0.55 | 0.40 |
| M | 0.085 | 0.150 | 0.110 |
| a | 0° | 8° | -- |
| All Dimensions in mm | | | |

Suggested Pad Layout

SOT23



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 2.0 |
| X | 0.8 |
| X1 | 1.35 |
| Y | 0.9 |
| Y1 | 2.9 |